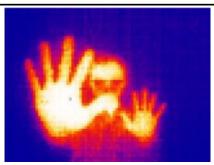


<Infrared Sensors>

MIR8060B1

THERMAL DIODE INFRARED SENSOR, 80x60 pixels, FOV 78°x53°



DESCRIPTION

The MIR8060B1 is an infrared sensor array applying unique thermal diode technology. It has an SPI interface and comes together with an IR lens and an ASIC with an OTP* memory that stores the sensitivity calibration data.

FEATURES

• Pixel resolution: 80x60 pixels

• FOV: 78° x 53°

• Flame rate: 4fps, 8fps

NETD : 100mK (Typ.) @4fpsSpectral range : 8 to 14 um

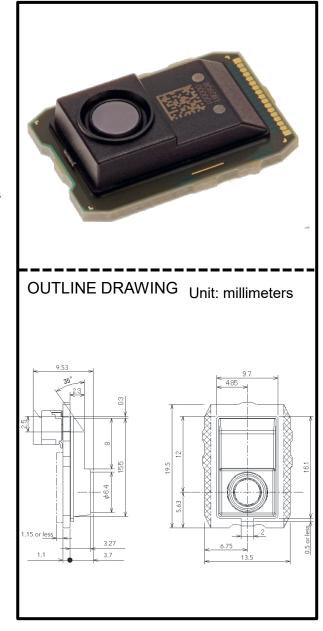
APPLICATIONS

• Security, Smart Building, People Counting, Temperature measurement, etc.

OTP*: one time programmable

Absolute maximum ratings

Symbol	Parameter	Min	Max	Unit
VDD	Power Supply Voltage	-0.3	3.8	>
MISO MOSI CLK NRST	Digital In-Out	-0.3	3.8	V
Tstg	Storage Temperature	-40	85	° C
Top Operation Temperature		-20	85	° C



Electrical Characteristics

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
ld	Current Consumption				50	mA
NETD	Noise Equivalent Temp. Difference	Vdd: 3.3V		100 @4fps		mK
FOVx	Field of View	Ta: 24° C		78		0
FOVy	Field of View			53		0

MIR8060B1

THERMAL DIODE INFRARED SENSOR, 80x60 pixels, FOV 78 $^{\circ}$ x53 $^{\circ}$

Main Revision for this Edition

		Revision		
No.	Date	Pages	Points	
*	11/Jul./2022	3	New Release	

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